# **MOSFET** - Power, Single **N-Channel, PQFN8**

# 100 V, 10.8 mΩ, 83 A

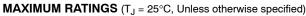
# Product Preview NTMFS010N10G

### Features

- Wide SOA for Linear Mode Operation
- Low R<sub>DS(on)</sub> to Minimize Conduction Loss
- High Peak UIS Current Capability for Ruggedness
- Small Footprint (5x6 mm) for Compact Design
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

## **Typical Applications**

• 48 V Hot Swap System, Load Switch, Soft Start, E-Fuse



Parar	Symbol	Value	Unit		
Drain-to-Source Breakdown Voltage			V <sub>(BR)DSS</sub>	100	V
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V
Continuous Drain Cur-	Steady	$T_{C} = 25^{\circ}C$	۱ <sub>D</sub>	83	А
rent $R_{\theta JC}$ (Note 2)	State	$T_{C} = 100^{\circ}C$	I <sub>D</sub>	58	А
Power Dissipation		$T_C = 25^{\circ}C$	PD	150	W
R <sub>θJC</sub> (Note 2)		$T_{C} = 100^{\circ}C$	PD	75	W
Continuous Drain Current $R_{\theta JA}$ (Note 1, 2)	Steady State	$T_C = 25^{\circ}C$	Ι <sub>D</sub>	11	А
		$T_{C} = 100^{\circ}C$	Ι <sub>D</sub>	8	А
Power Dissipation		$T_{C} = 25^{\circ}C$	PD	3	W
R <sub>θJA</sub> (Note 1, 2)		$T_{C} = 100^{\circ}C$	PD	1.5	W
Pulsed Drain Current	T <sub>A</sub> = 25°	C, t <sub>p</sub> = 10 μs	I <sub>DM</sub>	1247	А
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	–55 to +175	°C
Source Current (Body Diode)			۱ <sub>S</sub>	125	А
Single Pulse Drain-to-Source Avalanche Energy ( $I_{AV}$ = 38.8 A, L = 0.3 mH)			E <sub>AS</sub>	226	mJ
Lead Temperature Soldering Reflow for Sol- dering Purposes (1/8" from case for 10 s)			ΤL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Surface-mounted on FR4 board using 1 in<sup>2</sup> pad size, 1 oz Cu pad.
- 2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

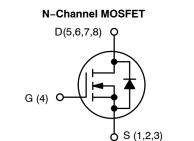
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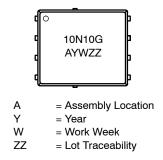
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V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX		
100 V	10.8 m $\Omega$ @ 10 V	83 A		





## MARKING DIAGRAM



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 5 of this data sheet.

#### **THERMAL CHARACTERISTICS**

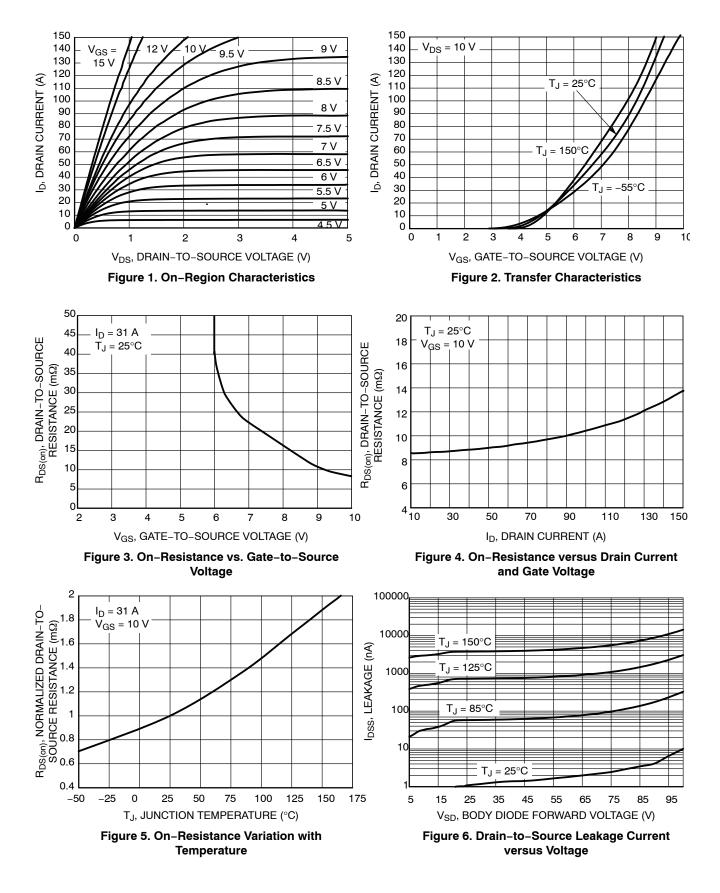
Symbol	Parameter	Мах	Unit
$R_{ extsf{ heta}JC}$	Junction-to-Case - Steady State	1.0	°C/W
$R_{ ext{ heta}JA}$	Junction-to-Ambient – Steady State	50	

### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}C$ unless otherwise noted)

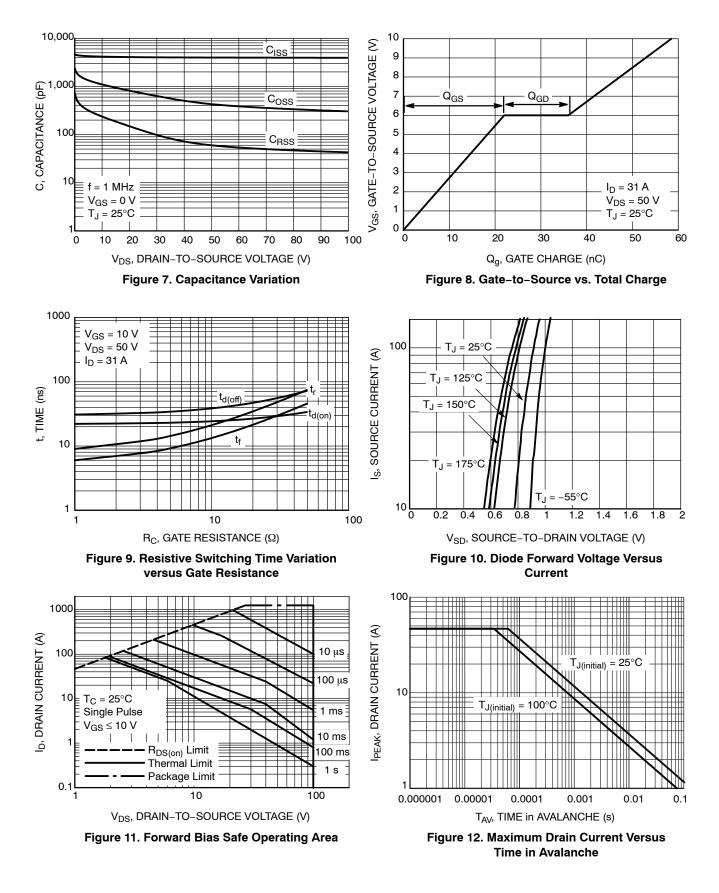
Symbol	Parameter	Test Conditions		Min	Тур	Max	Unit
OFF CHARAC	TERISTICS	•			•		-
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu$ A		100			V
$V_{(BR)DSS}/T_J$	Drain-to-Source Breakdown Voltage Temperature Coefficient	$I_D = 250 \ \mu A$ , ref to $25^{\circ}C$			87.9		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current		$T_J = 25^{\circ}C$			1	μA
		$V_{GS}$ = 0 V, $V_{DS}$ = 80 V	T <sub>J</sub> = 125°C			100	1
I <sub>GSS</sub>	Gate-to-Source Leakage Current	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V				±100	nA
ON CHARACT	ERISTICS (Note 3)	-					-
V <sub>GS(TH)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 1$	64 μΑ	2.0	3.0	4.0	V
V <sub>GS(TH)</sub> / T <sub>J</sub>	Negative Threshold Temperature Coefficient	$I_D = 164 \ \mu A$ , ref to 25°C			-9.2		mV/°C
R <sub>DS(on)</sub>	Drain-to-Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> =	31 A		8.6	10.8	mΩ
<sup>g</sup> FS	Forward Transconductance	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 31 A			21		S
R <sub>G</sub>	Gate-Resistance	V <sub>GS</sub> = 0 V, f = MHz			0.52		Ω
CHARGES & C	CAPACITANCES						
C <sub>ISS</sub>	Input Capacitance	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 50 V			3950		pF
C <sub>OSS</sub>	Output Capacitance				430		1
C <sub>RSS</sub>	Reverse Transfer Capacitance				60		
Q <sub>G(TOT)</sub>	Total Gate Charge				58.5		nC
Q <sub>GS</sub>	Gate-to-Source Charge	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 50 V, I <sub>D</sub> = 31 A			22		
Q <sub>GD</sub>	Gate-to-Drain Charge				14		-
Q <sub>OSS</sub>	Output Charge	V <sub>GS</sub> = 0 V, V <sub>DD</sub> = 50 V			41		1
	HARACTERISTICS (Note 3)						
t <sub>d(ON)</sub>	Turn–On Delay Time				23		ns
t <sub>r</sub>	Rise Time	Vcs = 10 V. Vcs = 50 V	ln = 31 A.		14		1
t <sub>d(OFF)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $V_{DS}$ = 50 V, $I_{D}$ = 31 A, $R_{G}$ = 4.7 $\Omega$			34		1
t <sub>f</sub>	Fall Time				9		
DRAIN-SOUR	CE DIODE CHARACTERISTICS				•		
V <sub>SD</sub>	Forward Diode Voltage	Voo - 0 V lo - 31 A	T <sub>J</sub> = 25°C		0.83	1.2	V
			T <sub>J</sub> = 125°C		0.7		1
t <sub>RR</sub>	Reverse Recovery Time	$V_{GS}$ = 0 V, dI <sub>S</sub> /dt = 300 A/µs, I <sub>S</sub> = 15 A			36		ns
Q <sub>RR</sub>	Reverse Recovery Charge				147		nC
t <sub>RR</sub>	Reverse Recovery Time	$V_{GS}$ = 0 V, dI_S/dt = 1000 A/µs, I_S = 15 A			24		ns
Q <sub>RR</sub>	Reverse Recovery Charge				288		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Switching characteristics are independent of operating junction temperatures.

# **TYPICAL CHARACTERISTICS**



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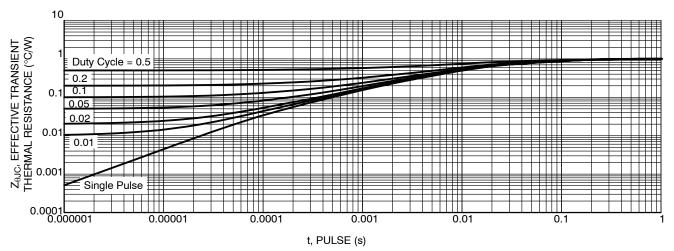


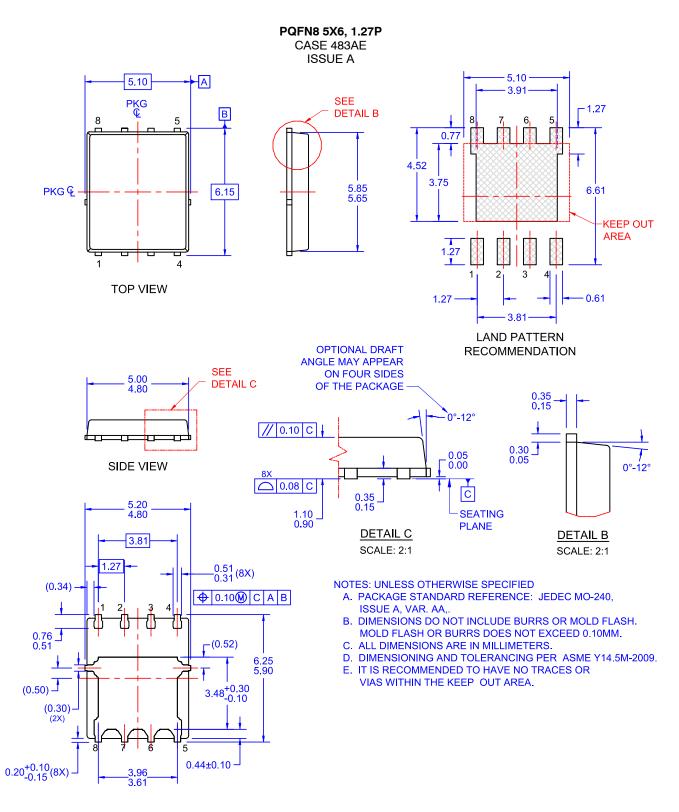
Figure 13. Transient Thermal Impedance

#### **ORDERING INFORMATION**

Device	Device Marking	Package	Shipping (Qty / Packing) <sup>†</sup>
NTMFS010N10GTWG	10N10G	PQFN8 (Pb-Free/Halogen Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### PACKAGE DIMENSIONS



BOTTOM VIEW

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